**Software Engineer**

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**Brief introduction** \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

Hi! I’m a software engineer.

I have 5 years of working in field as designer, developer, technical writer in the field of semiconductor industry (making chip). Thanks to that, I became an engineer with hands-on experience in OOP, C/C++, MFC programming, problem solving and root cause analysis, task break down and estimate skills. Understanding software development life cycle from specification reviews through to customer acceptance.

**Work experience** \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

**Shinkawa Vietnam Co., Ltd (***Nov. 2016 to Oct. 2020)*

Shinkawa commands the top global share as a manufacturer of bonders for the assembly process of semiconductor manufacturing (packaging).

I was responsible for modifying the UI/UX, maintain and develop new features based on design document, making test case and integrated testing software for Wire Bonder and Bump Bonder machine (making chip machine). I also work as a technical writer, analysis and researches customer's requirements, writing function specification, detail specification, manual documents.

**Highlight features I’ve been implemented:**

* STRIP MAP function (using SEMI G84 specification), Wire Bonder machine reads the 2D matrix code printed on the lead frame by the integrated camera, send this code to HOST and receives the corresponding strip map data from HOST. The strip map specifies which chips will be bonded or skipped on the lead frame. After that, Wire Bonder machine executes bonding according to this map data. When the lead frame is outloaded, Wire Bonder machine uploads bonding results to HOST. The format and methods in which strip map information shall be formatted and used to transfer information about a strip to and from equipment using the SECS/GEM interface standard. I directly design front-end, implement, testing and writing manual document.
* The SIMLOOP function provides a built-in list of loop shape, reduced working time with Automated loop shape optimization and Loop shape editor. Approx. 7% UPH improvements.
* CAD Data Making Tool, acts as an AutoCAD 2D 2014, 2015 plug-in, allowing the location of wires on the 2D chip design to be exported to \*.WCD file and then imported into the Wire Bonder machine to perform bonding. I was responsible for the development and maintenance of this tool after the previous member quit. I’ve made improvements to make it can work on AutoCAD 2D from 2014 to 2020 on both Windows 7/10 64-bit. CDMT developed by HTML, VB.NET, Object ARX and Auto Lisp languages.
* I joined SBB team as UI developer along with two other engineers. We trained about specification of Wafer Bump Bonder machine for 2 months at headquarters in Tokyo, Japan.

**Side project:**

* I have built a personal web server by using a raspberry pi 3b+ single-board computer. The purpose is to store, selectively share and publish data information. Thinks I used: raspberry pi 3b+, PHP7, HTML, No-IP Dynamic DNS. Link: http://nha.sytes.net

**Skills \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_**

* Experience in C/C++, MFC framework, Object-Oriented Programming.
* Having knowledge in Python programming, PyQT5 design (self-study).
* Basic understanding in embedded systems programming (Stm32f4 Arm Cortex 32-bit core, FreeRTOS and methodology such as task, memory management, synchronization and Task Communication Recommendations).
* Familiar with dev tools Visual Studio, STM32CubeMX, Qt Creator, make file, TFS, GitHub, Visual SourceSafe, IBM Lotus Notes, Tera term.
* Ability to troubleshoot issues to resolution. Good at problem solving and root cause analysis skills
* Ability to writing and reading English documents.
* Having passion to work, willing to relocate.

**Education** \_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_\_

**HCMC INDUSTRY AND TRADE COLLEGE** – Bachelor Degree *Nov. 2012 – Mar. 2016*

* **Specialty** – Information Technology.